

Specially designed for High-density SMT



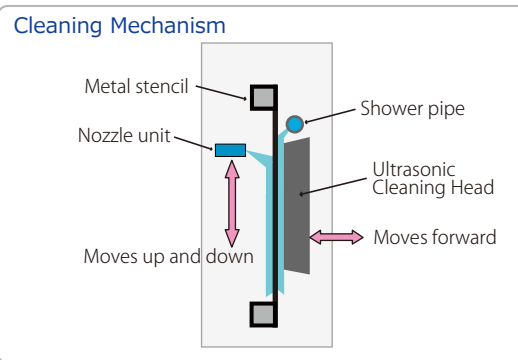
SC-BM500E(H/M/L)



The picture shows SC-BM500H-E (High-grade model).

Precise Cleaning

Ultrasonic combined to spray cleaning provides excellent solution for all kind of application including wafer bump and electroform stencils.



Wide range stencils applicable

Stencil size
320×320mm*



* Adapter required.



Stencil size
1000×740mm



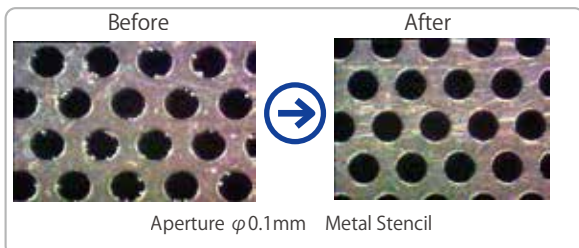
Stencils from 320mm × 320mm to 1000 × 740mm can be set easily. Recommended to customers using multiple types of stencils.

L : Simple
M : Standard
H : High-grade

Three types of specifications available to meet customer needs.

All models are equipped with a convenient touch panel screen.

Cleaning Ability



Specifications

Product No.	SC-BM500 (H/M/L) -E
Outside dimension	SC-BM500L-E: W 780 D 1,200 H 1,847mm SC-BM500M,H-E: W 780 D 1,260 H 2,250mm (including projecting parts.)
Weight	250kg
Power	AC 110, 120, 220, 240V 50/60Hz
Power consumption(VA)	550VA
Ultrasonic	40 k Hz 300W
Air	0.4MPa 600NL/min
Exhaust duct	5m/sec
Cleaning time	Approx. 3min.*
Drying time	Approx. 17min.*

* When using our recommended solvent HA-1285U.